

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**RECEIVED**  
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Inventors: Jian Zhou; Hua Chu  
Assignee: Nanometrics Incorporated  
Title: Method for Automatically De-Skewing of Multiple Layer Wafer for Improved Pattern Recognition  
Serial No.: 09/974,721 Filing Date: October 9, 2001  
Examiner: Colin M. Larose Group Art Unit: 1765  
Docket No.: NAN050 US Confirmation No.: 7841

Santa Clara, California  
August 3, 2006

Mail Stop RCE  
Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO OFFICE ACTION**

Dear Sir:

This Response to Office Action is responsive to the May 3, 2006, final Office Action, which has a statutorily shortened period for response that ends August 3, 2006. Please enter the following amendments before taking action on the merits of the above-referenced application.

08/04/2006 MBIZUNES 00000058 09974721  
02 FC:1202 50.00 OP

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